

ABSTRACT

WAFER PROCESSING FILM AND METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE BY USING WAFER PROCESSING FILM

There is provided a wafer processing film having a dicing and die bonding film comprising an adhesive layer and a removable adhesive film and capable of fully suppressing transferred marks otherwise generated in the adhesive layer when wound up in a roll. Specifically, a wafer processing film (10) comprises a removable adhesive film (14) that is composed of a long base film (11) and a long film-like removable adhesive layer (12) provided on the base film (11) and a long film-like adhesive layer (13) that is provided on the removable adhesive layer (12). The removable adhesive layer (12) contains a radiation-polymerizing compound and a photoinitiator. The removable adhesive layer (12) is not pre-cut into a shape corresponding to a ring frame (20), and the adhesive layer (13) is not pre-cut into a shape corresponding to a semiconductor wafer (W).

Figure 1